SCBS648A - DECEMBER 1995 - REVISED JANUARY 1997

- Output Ports Have Equivalent 25-Ω Series Resistors, So No External Resistors Are Required
- State-of-the-Art EPIC-IIB™ BiCMOS Design Significantly Reduces Power Dissipation
- Flow-Through Architecture Optimizes PCB Layout
- Latch-Up Performance Exceeds 500 mA Per JEDEC Standard JESD-17
- Typical V<sub>OLP</sub> (Output Ground Bounce) < 1 V at V<sub>CC</sub> = 5 V, T<sub>A</sub> = 25°C
- Package Options Include Plastic Small-Outline (DW) Package, Ceramic Chip Carriers (FK), and Plastic (NT) and Ceramic (JT) DIPs

#### description

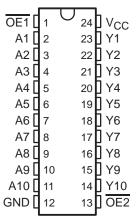
These 10-bit buffers or bus drivers provide a high-performance bus interface for wide data paths or buses carrying parity.

The 3-state control gate is a 2-input AND gate with active-low inputs so that if either output-enable (OE1 or OE2) input is high, all ten outputs are in the high-impedance state. The 'ABT2827 provide true data at their outputs.

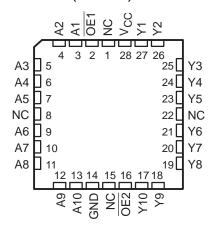
To ensure the high-impedance state during power up or power down,  $\overline{OE}$  should be tied to  $V_{CC}$  through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

The outputs, which are designed to source or sink up to 12 mA, include equivalent 25- $\Omega$  series resistors to reduce overshoot and undershoot.

#### SN54ABT2827 . . . JT PACKAGE SN74ABT2827 . . . DW OR NT PACKAGE (TOP VIEW)



## SN54ABT2827 . . . FK PACKAGE (TOP VIEW)



NC - No internal connection

The SN54ABT2827 is characterized for operation over the full military temperature range of –55°C to 125°C. The SN74ABT2827 is characterized for operation from –40°C to 85°C.



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

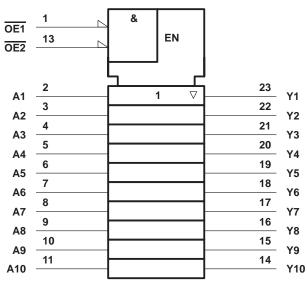
EPIC-IIB is a trademark of Texas Instruments Incorporated.



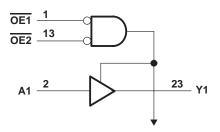
#### **FUNCTION TABLE**

	INPUTS	OUTPUT	
OE1	OE2	Α	Υ
L	L	L	L
L	L	Н	Н
Н	X	Χ	Z
Х	Н	Χ	Z

## logic symbol†



#### logic diagram (positive logic)



To Nine Other Channels

Pin numbers shown are for the DW, JT, and NT packages.

## absolute maximum ratings over operating free-air temperature range (unless otherwise noted)‡

Supp	oly voltage range, V <sub>CC</sub>	0.5 V to 7 V
Input	voltage range, V <sub>I</sub> (see Note 1)	0.5 V to 7 V
Volta	ge range applied to any output in the high or power-off state, VO	0.5 V to 5.5 V
Curre	ent into any output in the low state, IO: SN54ABT2827	96 mA
	SN74ABT2827	128 mA
Input	clamp current, I <sub>IK</sub> (V <sub>I</sub> < 0)	–18 mA
Outp	ut clamp current, I <sub>OK</sub> (V <sub>O</sub> < 0)	–50 mA
Pack	age thermal impedance, $\theta_{JA}$ (see Note 2): DW package	81°C/W
	NT package	67°C/W
Stora	age temperature range, T <sub>sto</sub>	–65°C to 150°C

<sup>‡</sup> Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.



<sup>&</sup>lt;sup>†</sup> This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.

<sup>2.</sup> The package thermal impedance is calculated in accordance with EIA/JEDEC Std JESD51, except for through-hole packages, which use a trace length of zero.

## recommended operating conditions (see Note 3)

		SN54AE	SN54ABT2827		T2827	UNIT
		MIN	MAX	MIN	MAX	UNIT
VCC	Supply voltage	4.5	5.5	4.5	5.5	V
VIH	High-level input voltage	2	EN	2		V
VIL	Low-level input voltage		0.8		0.8	V
VI	Input voltage	0<	Vcc	0	VCC	V
IOH	High-level output current	\\ \( \)	-12		-12	mA
loL	Low-level output current	200	12		12	mA
Δt/Δν	Input transition rise or fall rate	A)	5		5	ns/V
TA	Operating free-air temperature	-55	125	-40	85	°C

NOTE 3: Unused inputs must be held high or low to prevent them from floating.

# electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

DADAMETED	TEST COND	1	T <sub>A</sub> = 25°0		SN54AB	T2827	SN74AB	T2827	UNIT	
PARAMETER	TEST COND	IIIONS	MIN	TYP <sup>†</sup>	MAX	MIN	MAX	MIN	MAX	UNII
VIK	V <sub>CC</sub> = 4.5 V,	I <sub>I</sub> = -18 mA			-1.2		-1.2		-1.2	V
	V <sub>CC</sub> = 4.5 V,	I <sub>OH</sub> = -1 mA	2.5			2.5		2.5		
Vali	V <sub>CC</sub> = 5 V,	I <sub>OH</sub> = -1 mA	3			3		3		V
Voн	V <sub>CC</sub> = 4.5 V	$I_{OH} = -3 \text{ mA}$	2.4			2.4		2.4		V
	VCC = 4.5 V	$I_{OH} = -12 \text{ mA}$	2			2		2		
VOL	V <sub>CC</sub> = 4.5 V	I <sub>OL</sub> = 12 mA			0.8		0.8		0.8	V
V <sub>hys</sub>				100						mV
ΙĮ	$V_{CC} = 0 \text{ to } 5.5 \text{ V},$	$V_I = V_{CC}$ or GND			±1		#1		±1	μΑ
lozh	V <sub>CC</sub> = 5.5 V,	V <sub>O</sub> = 2.7 V			10‡		10		10‡	μΑ
lozL	$V_{CC} = 5.5 V$ ,	$V_0 = 0.5 V$			-10‡		<b>–</b> 10		-10‡	μΑ
l <sub>off</sub>	$V_{CC} = 0$ ,	$V_I$ or $V_O \le 4.5 \text{ V}$			±100		. 6		±100	μΑ
ICEX	V <sub>CC</sub> = 5.5 V, V <sub>O</sub> = 5.5 V	Outputs high			50	3	50		50	μΑ
ΙΟ <sup>§</sup>	V <sub>CC</sub> = 5.5 V,	V <sub>O</sub> = 2.5 V	-50	-140	-225‡	-50	-225‡	-50	-225‡	mA
	V <sub>CC</sub> = 5.5 V,	Outputs high		80	250	Q	250		250	μΑ
lcc	$I_{O} = 0$ ,	Outputs low		35	40‡		40‡		40‡	mA
	$V_I = V_{CC}$ or GND	Outputs disabled		80	250		250		250	μΑ
	V <sub>CC</sub> = 5.5 V,	Outputs enabled			1.5		1.5		1.5	mA
Δlcc¶	One input at 3.4 V, Other inputs at	Outputs disabled			50		50		50	μΑ
	V <sub>CC</sub> or GND	Control inputs			1.5		1.5		1.5	mA
C <sub>i</sub>	V <sub>I</sub> = 2.5 V or 0.5 V			4						pF
Co	V <sub>O</sub> = 2.5 V or 0.5 V			8.5						pF

 $<sup>^{\</sup>dagger}$  All typical values are at V<sub>CC</sub> = 5 V, T<sub>A</sub> = 25°C.



<sup>‡</sup> This data sheet limit may vary among suppliers.

<sup>§</sup> Not more than one output should be tested at a time, and the duration of the test should not exceed one second.

<sup>¶</sup> This is the increase in supply current for each input that is at the specified TTL voltage level rather than V<sub>CC</sub> or GND.

## SN54ABT2827, SN74ABT2827 10-BIT BUFFERS/DRIVERS WITH 3-STATE OUTPUTS

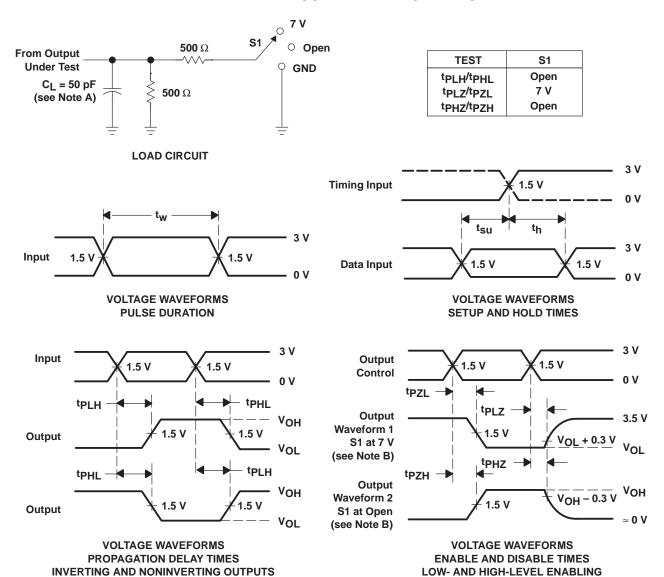
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switching characteristics over recommended ranges of supply voltage and operating free-air temperature,  $C_L = 50$  pF (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V <sub>(</sub>	CC = 5 V 4 = 25°C	<u>/,</u>	SN54AB	T2827	SN74AB	T2827	UNIT
	(IIII O1)	(0011 01)	MIN	TYP	MAX	MIN	MAX	MIN	MAX	
t <sub>PLH</sub>	А	V	1.1	3.3	5.1	1.1	5.6	1.1	5.5	20
<sup>t</sup> PHL	A	1	1.1	2.7	4.5	1.1	5.2	1.1	5.1	ns
<sup>t</sup> PZH	<u> </u>		1	4	5.9	1	6.8	1	6.7	
<sup>t</sup> PZL	ŌĒ	Y	1	4.2	6.8	37	8	1	7.8	ns
t <sub>PHZ</sub>	ŌĒ		2	5.3	6.7	0 2	7.4	2	7.2	
t <sub>PLZ</sub>	OE	T T	1.3	4.8	7.2	1.3	8.5	1.3	7.5	ns



#### PARAMETER MEASUREMENT INFORMATION



NOTES: A. C<sub>I</sub> includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR  $\leq$  10 MHz,  $Z_O$  = 50  $\Omega$ ,  $t_f \leq$  2.5 ns,  $t_f \leq$  2.5 n
- D. The outputs are measured one at a time with one transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms



## PACKAGE OPTION ADDENDUM

10-Dec-2020

#### PACKAGING INFORMATION

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Orderable Device	Status	Package Type	Package Drawing	Pins	Package Qty	Eco Plan	Lead finish/ Ball material	MSL Peak Temp	Op Temp (°C)	Device Marking (4/5)	Samples
SN74ABT2827DW	ACTIVE	SOIC	DW	24	25	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	ABT2827	Samples
SN74ABT2827DWR	ACTIVE	SOIC	DW	24	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	ABT2827	Samples

(1) The marketing status values are defined as follows:

**ACTIVE:** Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

(2) RoHS: TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

**Green:** TI defines "Green" to mean the content of Chlorine (Cl) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

- (3) MSL, Peak Temp. The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.
- (4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.
- (5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.
- (6) Lead finish/Ball material Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

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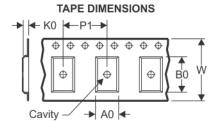
10-Dec-2020

## **PACKAGE MATERIALS INFORMATION**

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## TAPE AND REEL INFORMATION





A0	Dimension designed to accommodate the component width
	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

## QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



#### \*All dimensions are nominal

Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74ABT2827DWR	SOIC	DW	24	2000	330.0	24.4	10.75	15.7	2.7	12.0	24.0	Q1

www.ti.com 5-Jan-2022



#### \*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74ABT2827DWR	SOIC	DW	24	2000	350.0	350.0	43.0

## PACKAGE MATERIALS INFORMATION

www.ti.com 5-Jan-2022

#### **TUBE**



#### \*All dimensions are nominal

Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	T (µm)	B (mm)
SN74ABT2827DW	DW	SOIC	24	25	506.98	12.7	4826	6.6

DW (R-PDSO-G24)

## PLASTIC SMALL OUTLINE



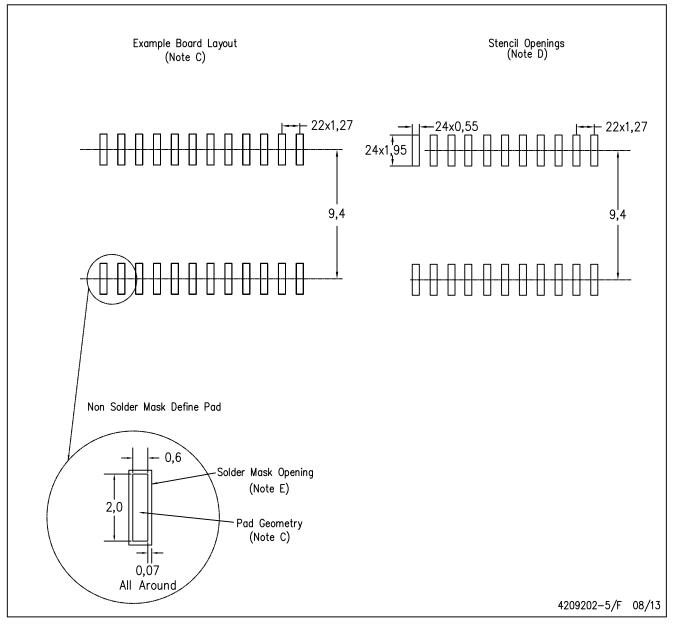
NOTES: A. All linear dimensions are in inches (millimeters). Dimensioning and tolerancing per ASME Y14.5M-1994.

- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
- D. Falls within JEDEC MS-013 variation AD.



DW (R-PDSO-G24)

PLASTIC SMALL OUTLINE



NOTES:

- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Refer to IPC7351 for alternate board design.
- D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525
- E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.



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